ABSTRACT

There is provided a mounting apparatus capable of forming dicing tapes in the process of feeding-out a strip material, and sticking the dicing tape to a ring frame to fix a semiconductor wafer.

The mounting apparatus 10 sticks the dicing tape to the ring frame RF to fix the semiconductor wafer to the ring frame in a state that the ring frame RF and the semiconductor wafer W are disposed on a table 11. The mounting apparatus 10 includes a pre-cut means 13 for forming a cut L in a state of half cut in a film FL of a strip material A to form a dicing tape T in the process of feeding out the strip material A and a sticking means 34 for peeling off the dicing tape from a base sheet S to stick the dicing tape to the ring frame RF.